

FORM PTO-1595 (Modified)
(Rev. 6-93)
OMB No. 0651-0011 (exp. 4/94)
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U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

06-14-2000

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To the Honorable Commissioner of Patent

101381234

ached original documents or copy thereof.

1. Name of conveying party(ies):

YUN, Jong Young

2. Name and address of receiving party(ies):

Name: Samsung Electronics Co., Ltd.

Address: 416, Maetan-dong, Paldal-gu,

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

City: Suwon-city, Kyungki-do, State/Prov.:

Country: Republic of Korea ZIP:

Execution Date: May 8, 2000

Additional name(s) & address(es)

☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

09/584766

If this document is being filed together with a new application, the execution date of the application is: May 8, 2000

Patent Application No.

Filing date

B. Patent No.(s)

NEW

JUNE 1, 2000

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: ADAM C. VOLENTINE

Registration No. 33289

Address: JONES VOLENTINE, LLP

12200 SUNRISE VALLEY DRIVE, SUITE 150

City: RESTON State/Prov.: VA

Country: U.S.A. ZIP: 20191

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☐ Authorized to be charged to deposit account

8. Deposit account number:

50-0238

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

ADAM C. VOLENTINE

Name of Person Signing

Signature

JUNE 1, 2000

Date

Total number of pages including cover sheet, attachments, and

3

PATENT

REEL: 010839 FRAME: 0502

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s)
of Inventor(s)

YUN, Jong Young

and

Insert Name(s)
of Assignee(s)

the undersigned hereby sell(s) and assign(s) to

SAMSUNG ELECTRONICS CO., LTD.

Address

of 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of
Invention

METHOD AND APPARATUS FOR FORMING HSG-Si LAYER ON A WAFER

Date of Signing
of Application

for which an application for patent in the United States of America has been executed by the undersigned

on May 8, 2000

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) to Raymond C. Jones, Reg. No. 34,631 and Adam C. Volentine, Reg. No. 33,289, members of the firm of JONES VOLENTINE, L.L.P. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 2000.05.08, Name of Inventor Jong Young YUN
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____
Date _____, Name of Inventor _____

(Note regarding Witnessing and/or Acknowledgment: Acknowledgment before a United States Consul is preferred but not required. If not acknowledged, then it is recommended that the execution by the Inventor(s) be witnessed by at least two witnesses who sign here. However, the current practice of the U.S. Patent and Trademark Office is to record an Assignment even if it has not been acknowledged and/or witnessed.)

Witness _____
Witness _____

ACKNOWLEDGMENT

_____ } ss

This _____ day of _____, 19____, before me personally came the above-named

_____ to me personally known as the individual(s)
who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

Official Signature _____

SEAL

Official Title _____

Applicant Reference No.: _____ Atty Docket No.: SEC.711

Serial No.: _____ Filing Date: _____